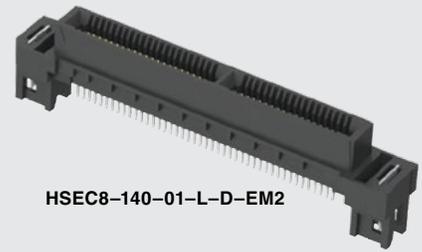




HSEC8-130-01-S-D-EM2



HSEC8-140-01-L-D-EM2

HSEC8-EM SERIES

(0.80 mm) .0315"

EDGE MOUNT EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-EM

Insulator Material: Liquid Crystal Polymer
Contact: BeCu

Plating: Au or Sn over 50 μm (1.27 μm) Ni

Operating Temp: -55 °C to +125 °C

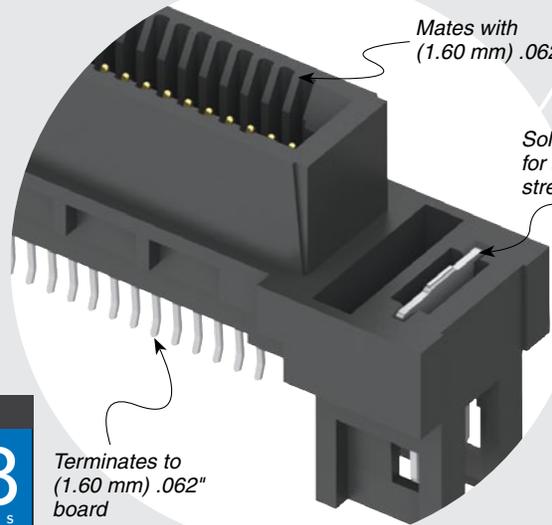
Lead-Free Solderable: Yes

RoHS Compliant: Yes

Yes

Card Mates: (1.60 mm) .062" thick card, HSC8

Cable Mates: ECDP



Mates with (1.60 mm) .062" cards

Solder Tab for added strength

Terminates to (1.60 mm) .062" board

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

HIGH-SPEED CHANNEL PERFORMANCE

HSEC8-EM

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

28
Gbps

ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.



10, 20, 30, 40, 50, 60

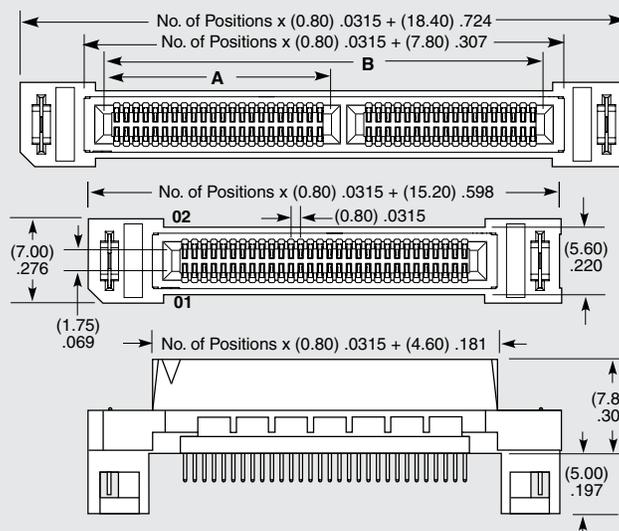
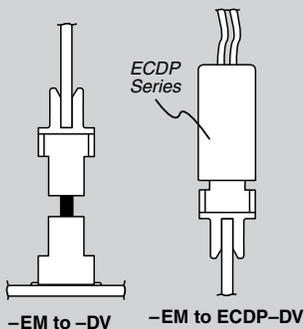
POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

-S
= 30 μm (0.76 μm) Gold on contact, Matte Tin on tail

-EM2
= (1.60 mm) .062" thick PCB

APPLICATIONS



OTHER SOLUTIONS

Polarized mates for ECDP Series twinax cables

CONNECTOR	CABLE
HSEC8-113	ECDP-08
HSEC8-125	ECDP-16
HSEC8-137	ECDP-24
HSEC8-149	ECDP-32

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.